HCPL2630 DUAL-CHANNEL OPTOCOUPLER/OPTOISOLATOR

SOOS010 D2969, NOVEMBER 1986

- Gallium Arsenide Phosphide LED Optically Coupled to an Integrated Circuit Detector
- Compatible with TTL and LSTTL Inputs
- Low Input Current Required for On-State Output . . . 5 mA Max
- High-Voltage Electrical Insulation . . . 3000 V DC Min

- High-Speed Switching . . . 75 ns Max
- Directly Interchangeable with Hewlett Packard HCPL2630
- UL Recognized . . . File Number E65085

description

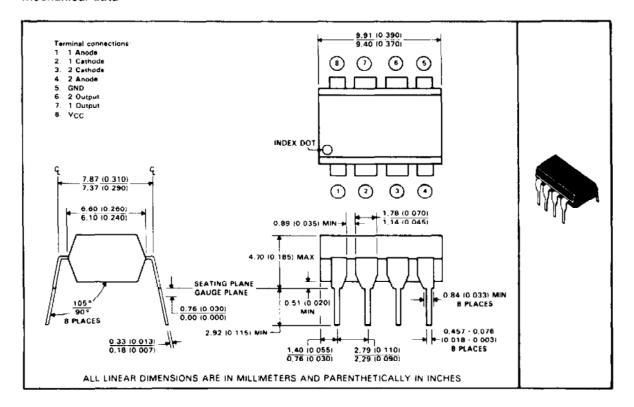
The HCPL2630 is a dual optocoupler designed for use in high-speed digital interfacing applications that require high-voltage isolation between the input and output. Applications include line receivers, microprocessors or computer interface, and other control systems.

Each channel of the HCPL2630 optocoupler consists of a GaAsP light-emitting diode and an integrated light detector composed of a photodiode, a high-gain amplifier, and a Schottky-clamped open-collector output transistor. An input diode forward current of 5 milliamperes will switch the output transistor low, providing an on-state drive current of 13 milliamperes (eight 1.6-milliampere TTL loads).

The device is mounted in a standard 8-pin dual-in-line plastic package.

The HCPL2630 is characterized for operation over the temperature range of 0°C to 70°C.

mechanical data

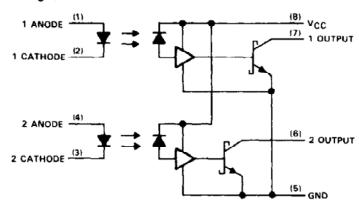


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HCPL2630 DUAL-CHANNEL OPTOCOUPLER/OPTOISOLATOR

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC
Reverse input voltage
Output voltage
Peak forward input current, each channel (≲1 ms duration)
Average forward input current, each channel
Output current, each channel
Output power dissipation
Storage temperature range 55 °C to 125 °C
Operating free-air temperature range
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds

recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Output supply voltage (see Note 1)	4.5	5	5.5	V
lF(on)	Input forward current to turn output on	6.3		15	mA
F(off)	Input forward current to turn output off	0		250	μА
OL	Low-level (on-state) autput current			13	mA
TA	Operating free-air temperature	0		70	°C

NOTE 1: All voltage values are with respect to GND (pin 5).

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
VF	Input forward voltage	lF = 10 mA,	TA = 25°C		1.6	1.75	V
αVF	Temperature coefficient of forward voltage	I _F = 10 mA	-		- 1.B		mV/°C
VBR	Input reverse breakdown voltage	I _R = 10 μA.	$T_A = 25$ °C	5			V
VOL	Low-level output voltage	$V_{CC} = 5.5 \text{ V},$	I _F = 5 mA,	0.23	0.22	0.6	v
		1 _{OL} = 13 mA			0.23	0.0	
ЮН	High-level output current	$V_{CC} = 5.5 V_{c}$	$V_0 = 5.5 V$,			250	μΔ
		IF = 250 μA					
ІССН	Supply current, high-level output	V _{CC} - 5.5 V.	lr = 0		20	30	mΑ
CCL	Supply current, low-level output	V _{CC} = 5.5 V,	I _F = 10 mA		26	36	mA
		$V_{ } = 500 V$,	t = 5 s,				
I _{II}	Input-input insulation leakage current	T _A ≈ 25°C	RH = 45%.	0.005	0.005		μΑ
		See Note 2					
	Input-output insulation leakage current	V _{IO} = 3000 V.	t = 5 s.				
110		T _A ≈ 25°C.	RH - 45%,			1	ДД
		See Note 1					
	Input-input resistance	V _{II} = 500 V,	TA - 25°C,	T	1011		Ω
r H	input-input resistance	See Note 2			10		` ''
rio	input-output résistance	V _{(O} = 500 V.	TA = 25°C.	1012		_	Ω
		See Note 1		10	10		
Ci	Input capacitance	Vr = 0.	f = 1 MHz		60		pF
Cii	Input input capacitance	V _F = 0,	f = 1 MHz		0.25		рF
Cio	Input-output capacitance	f = 1 MHz,	TA ≈ 25°C.	0.6		pF	
~10		See Note 1			0.0		Pr

 $^{^{\}dagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

NOTES 1. These parameters are measured between pins 1, 2, 3, and 4 shorted together and pins 5, 6, 7, and 8 shorted together

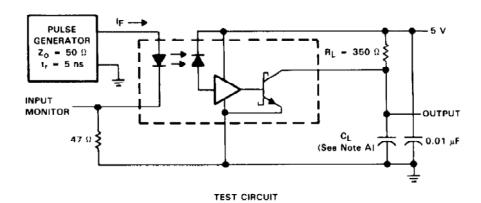
2. These parameters are measured between pins 1 and 2 shorted together and pins 3 and 4 shorted together.

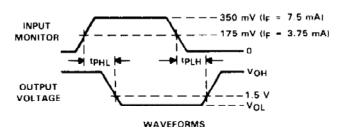
switching characteristics at VCC = 5 V. TA = 25 °C

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
₹PLH	Propagation delay time, low-to-high-level output, from LED input	IF - 7.5 mA, CL = 15 pF,	R _L = 350 Ω. See Figure 1		42	75	ns
tPHL	Propagation delay time, high-to-low level output, from LED input	IF = 75 mA, CL = 15 pF,	R _L = 350 Ω. See Figure 1		42	75	nŝ
tr	Rise time	IF : 7.6 mA. CL = 15 pF	R _L = 350 Ω.		20		ns
tſ	Fall time	IF = 7.5 mA, CL = 15 pF	R _L = 350 Ω,		30		ns
d√CM (H	Common-mode input transient immunity, high-level output	$\Delta V_{CM} = 10 \text{ V}, I_F = 0,$ $R_L = 350 \Omega,$ See Note 3 and Figure 2			50		V/μs
dVCM (L)	Common-mode input transient immunity. low-level output	$\Delta V_{CM} = -10 \text{ V. IF} = 5 \text{ mA},$ $R_L = 350 \Omega,$ See Note 3 and Figure 2			- 150		V/μs

NOTE 3: Common-mode input transient immunity, high-level output, is the maximum rate of rise of the common-mode input voltage that does not cause the output voltage to drop below 2 V. Common-mode input transient immunity, low-level output, is the maximum rate of fall of the common-mode input voltage that does not cause the output voltage to rise above 0.8 V.

PARAMETER MEASUREMENT INFORMATION (EACH CHANNEL)





NOTE A: Ct is approximately 16 pF, which includes probe and stray wiring capacitances.

FIGURE 1. tPLH AND tPHL FROM LED INPUT TEST CIRCUIT AND WAVEFORMS

PARAMETER MEASUREMENT INFORMATION (EACH CHANNEL)

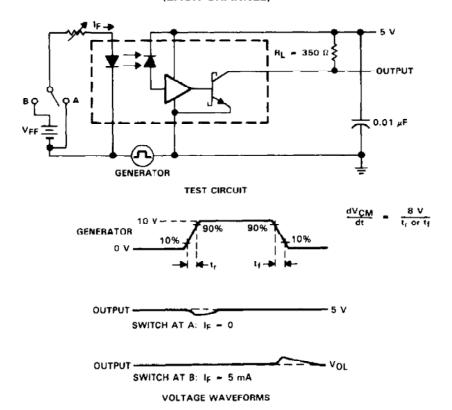


FIGURE 2. TRANSIENT IMMUNITY TEST CIRCUIT AND WAVEFORMS

TYPICAL APPLICATION INFORMATION

A ceramic capacitor $(0.01~\mu\text{F}\ \text{to}\ 0.1~\mu\text{F})$ should be connected between pins 8 and 5 to stabilize the high-gain amplifier. The total lead length between the capacitor and the optocoupler should not exceed 20 mm (0.8~inches). Failure to provide a bypass capacitor may result in impaired switching characteristics.

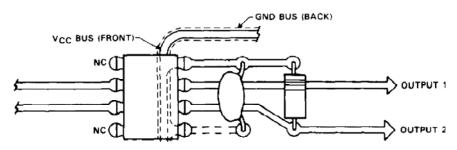
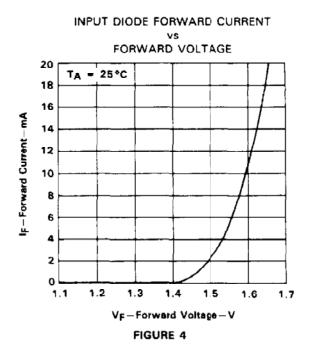
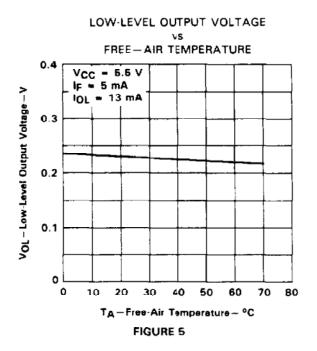


FIGURE 3. RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT

TYPICAL CHARACTERISTICS





HIGH-LEVEL OUTPUT CURRENT

FREE-AIR TEMPERATURE

VCC = 5.5 V
VO = 5.5 V
IF = 250 µA

0 10 20 30 40 50 60 70 80

TA = Free-Air Temperature = °C

FIGURE 6

TYPICAL CHARACTERISTICS

PROPAGATION DELAY TIME FROM LED INPUT

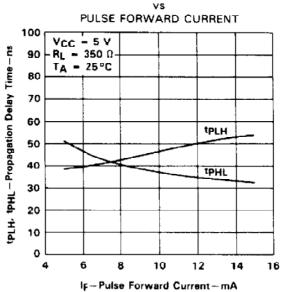


FIGURE 7

PROPAGATION DELAY TIME FROM LED INPUT

VS

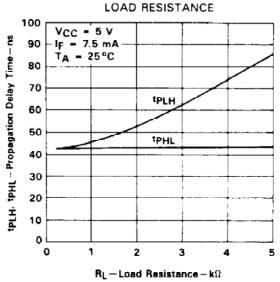


FIGURE 8

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